

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph at page 5, lines 9 - 14, as follows:

2) The next layer of the BLM is a reaction barrier layer which is solderable by the molten solder but reacts react slowly (limited reaction) to allow for multiple reflow cycles (or rework cycles) without being totally consumed. This layer is typically on the order of thousands of angstroms to microns in thickness.

Please amend the paragraph at page 16, lines 19 - 30, as follows:

In accordance with the present invention, a preferred adhesion layer 14 is Cr, TiW or Ti, [[,]] which is preferably either sputtered or evaporated, at a preferred thickness of about 100 to 3000 angstroms. The thickness of the adhesion layer 12 can vary widely as long as both good adhesion and good barrier properties are maintained. If blanket TiW is deposited and subsequently etched as the final step in forming the patterned BLM structure 11, the film thickness should be minimized consistent with adequate performance. An alternative adhesion layer is Cr or Ti at a thickness of about 100 to 3000 angstroms.